InterPACK 2024

ASME International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

October 8-10, 2024

Holiday Inn San Jose - Silicon Valley
San Jose, CA

ASME CONFERENCE

International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

October 8-10, 2024

Location: The Holiday Inn San Jose-Silicon Valley

CALL FOR ABSTRACTS

DEADLINE — February 19, 2024 - SUBMIT YOURS TODAY!

Submit Abstracts →

Since 1992, InterPACK has been a premier international conference for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics and photonics packaging and heterogeneous integrated systems. InterPACK is a flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of InterPACK has been highly beneficial in promoting synergy between industry, government, and academia. In addition to technical presentations and exhibitions, InterPACK 2024 will include 6 plenary talks, panel discussions, workshops, career networking event, keynotes and technology talks, and an industry-national laboratory-academia joint interactive presentations session. Abstracts (400 words minimum, 650 words maximum) for original papers are solicited in the general track areas of:

Technical Tracks:

Heterogeneous Integration	Data Centers and Modular Edge Systems
Electronics Packaging	Power/RF Electronics and Photonics
Multiscale Thermal Transport and Energy Storage	Flexible, Wearable, and Printed Electronics
Transportation Systems, AI, and Machine Learning	Interactive Presentations

Publication Schedule:

Abstract Submissions	**February 19, 2024**
Notification of Abstract Acceptance	March 4, 2024

For more information about ASME's InterPACK Conference, the full publication schedule, and presentation guidelines, go to: **http://event.asme.org/interpack**